



General Description

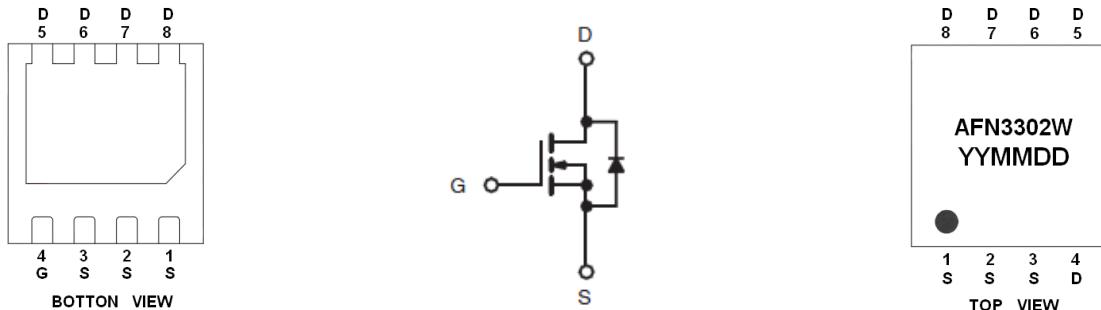
AFN3302W, N-Channel enhancement mode MOSFET, uses Advanced Trench Technology to provide excellent $R_{DS(ON)}$, low gate charge.

These devices are particularly suited for low voltage power management, such as smart phone and notebook computer and other battery powered circuits, and low in-line power loss are needed in commercial industrial surface mount applications.

Features

- $I_D=14A, R_{DS(ON)}=14m\Omega @ V_{GS}=4.5V$
- $I_D=12A, R_{DS(ON)}=18m\Omega @ V_{GS}=2.5V$
- $I_D=10A, R_{DS(ON)}=26m\Omega @ V_{GS}=1.8V$
- Super high density cell design for extremely low $R_{DS(ON)}$
- Exceptional on-resistance and maximum DC current capability
- DFN3X3-8L package design

Pin Description (DFN3X3-8L)



Application

- DC-DC Converter
- POL

Pin Define

Pin	Symbol	Description
1	S	Source
2	S	Source
3	S	Source
4	G	Gate
5	D	Drain
6	D	Drain
7	D	Drain
8	D	Drain

Ordering Information

Part Ordering No.	Part Marking	Package	Unit	Quantity
AFN3302WFN338RG	AFN3302W	DFN3X3-8L	Tape & Reel	5000 EA

※ YY year code

※ MM month code

※ DD date code

※ AFN3302WFN338RG : 13" Tape & Reel ; Pb-Free ; Halogen-Free



**Alfa-MOS
Technology**

**AFN3302W
20V N-Channel
Enhancement Mode MOSFET**

Absolute Maximum Ratings

($T_A=25^\circ\text{C}$ Unless otherwise noted)

Parameter	Symbol	Value		Unit
Drain-Source Voltage	V_{DSS}	20		V
Gate –Source Voltage	V_{GSS}	± 12		V
Continuous Drain Current($T_J=150^\circ\text{C}$)	I_D	14	A	
		10		
Pulsed Drain Current	I_{DM}	40		A
Continuous Source Current(Diode Conduction)	I_S	1.6		A
Power Dissipation	P_D	28	15	W
		3.2	2.0	
Operating Junction Temperature	T_J	150		$^\circ\text{C}$
Storage Temperature Range	T_{STG}	-55/150		$^\circ\text{C}$
Thermal Resistance Junction-to-Case (Drain)	$R_{\theta JC}$	5	$^\circ\text{C}/\text{W}$	
Thermal Resistance-Junction to Ambient	$R_{\theta JA}$	40		

Electrical Characteristics

($T_A=25^\circ\text{C}$ Unless otherwise noted)

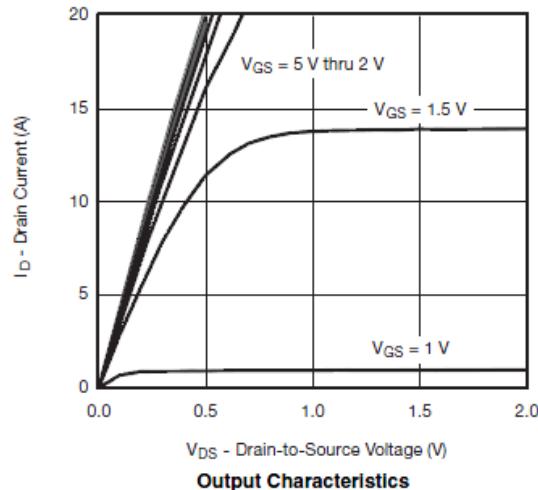
Parameter	Symbol	Conditions	Min.	Typ	Max.	Unit
Static						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS}=0\text{V}, I_D=250\mu\text{A}$	20			V
Gate Threshold Voltage	$V_{GS(\text{th})}$	$V_{DS}=V_{GS}, I_D=250\mu\text{A}$	0.4		1.0	
Gate Leakage Current	I_{GSS}	$V_{DS}=0\text{V}, V_{GS}=\pm 12\text{V}$			± 100	nA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS}=16\text{V}, V_{GS}=0\text{V}$			1	uA
		$V_{DS}=16\text{V}, V_{GS}=0\text{V}$ $T_J=85^\circ\text{C}$			10	
On-State Drain Current	$I_{D(on)}$	$V_{DS}\geq 5\text{V}, V_{GS}=10\text{V}$	40			A
Drain-Source On-Resistance	$R_{DS(on)}$	$V_{GS}=4.5\text{V}, I_D=14\text{A}$		11	14	mΩ
		$V_{GS}=2.5\text{V}, I_D=12\text{A}$		15	18	
		$V_{GS}=1.8\text{V}, I_D=10\text{A}$		20	26	
Forward Transconductance	g_{FS}	$V_{DS}=5\text{V}, I_D=3.6\text{A}$		10		S
Diode Forward Voltage	V_{SD}	$I_S=1.6\text{A}, V_{GS}=0\text{V}$		0.85	1.5	V
Dynamic						
Total Gate Charge	Q_g	$V_{DS}=10\text{V}, V_{GS}=4.5\text{V}$ $I_D=4.0\text{A}$		8.2	14	nC
Gate-Source Charge	Q_{gs}			1.2		
Gate-Drain Charge	Q_{gd}			1.0		
Input Capacitance	C_{iss}	$V_{DS}=10\text{V}, V_{GS}=0\text{V}$ $f=1\text{MHz}$		850		pF
Output Capacitance	C_{oss}			120		
Reverse Transfer Capacitance	C_{rss}			60		
Turn-On Time	$t_{d(on)}$	$V_{DD}=10\text{V}, R_L=2.2\Omega$ $I_D=4.0\text{A}, V_{GEN}=4.5\text{V}$		10	16	ns
	t_r			16	25	
Turn-Off Time	$t_{d(off)}$			31	45	
	t_f			10	16	



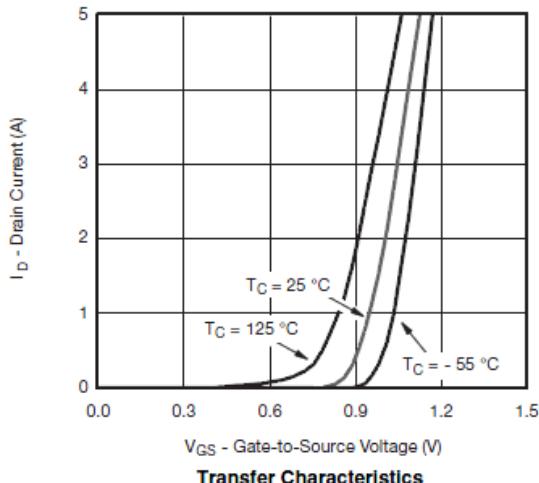
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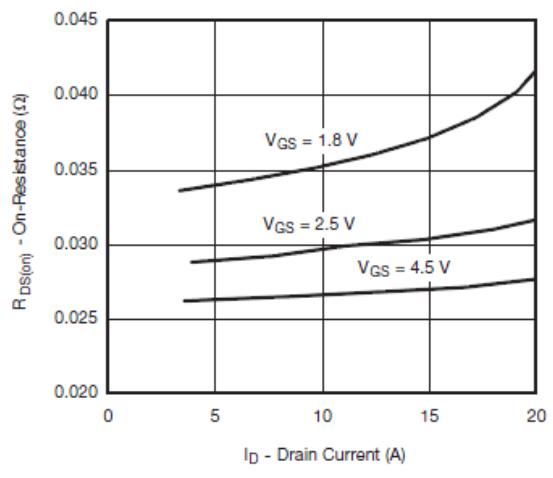
Typical Characteristics



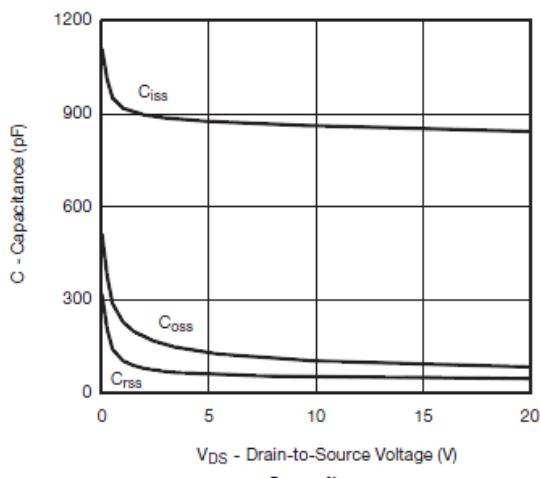
Output Characteristics



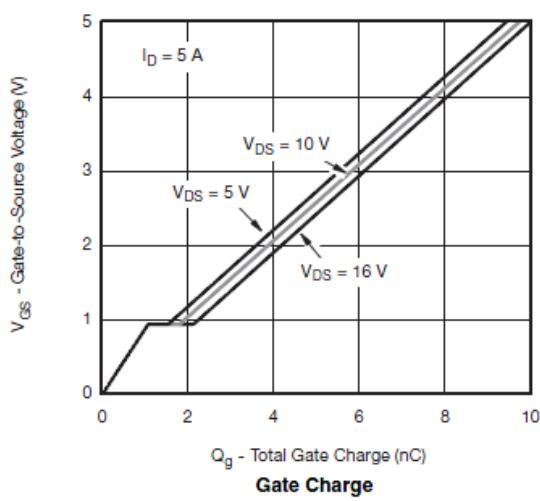
Transfer Characteristics



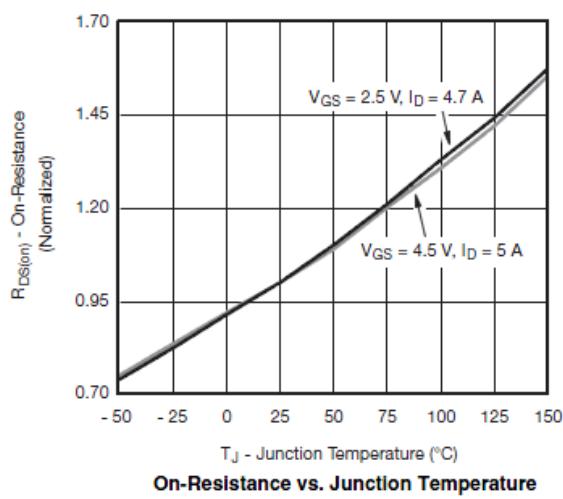
On-Resistance vs. Drain Current and Gate Voltage



Capacitance



Gate Charge



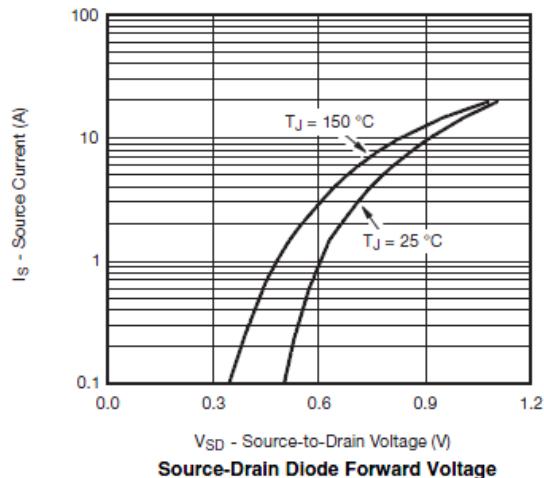
On-Resistance vs. Junction Temperature



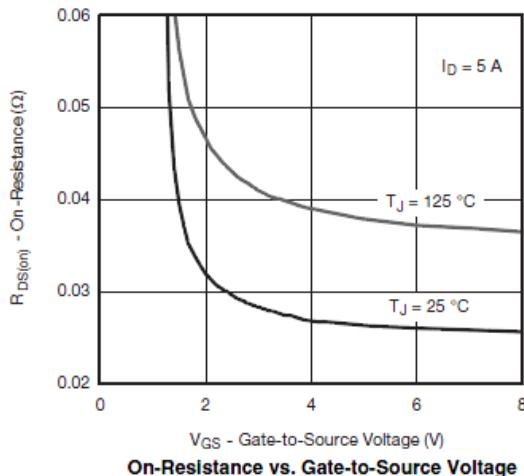
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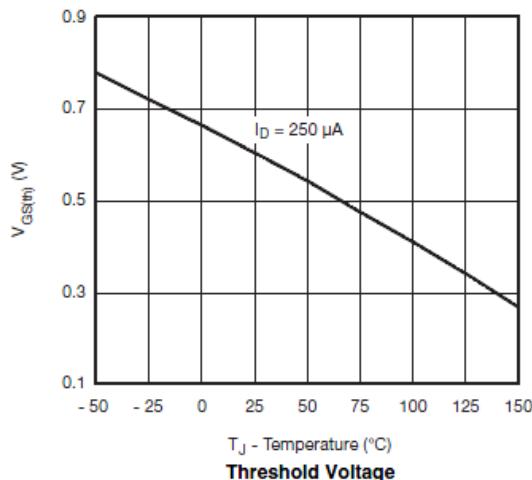
Typical Characteristics



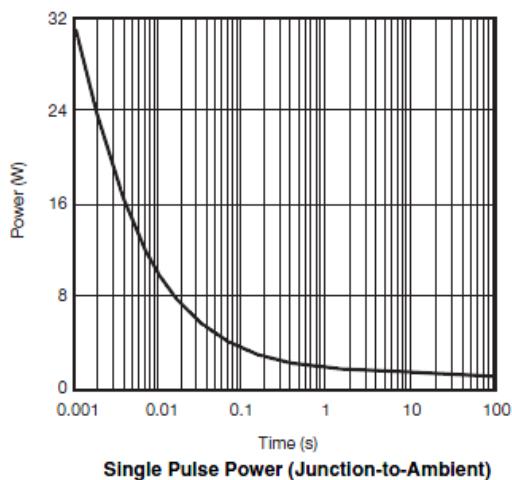
Source-Drain Diode Forward Voltage



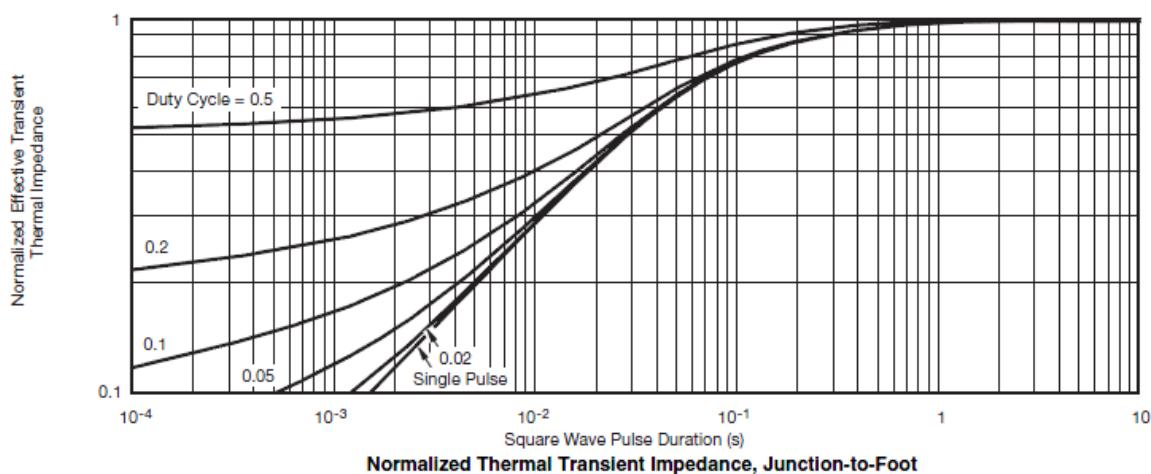
On-Resistance vs. Gate-to-Source Voltage



Threshold Voltage



Single Pulse Power (Junction-to-Ambient)



Normalized Thermal Transient Impedance, Junction-to-Foot

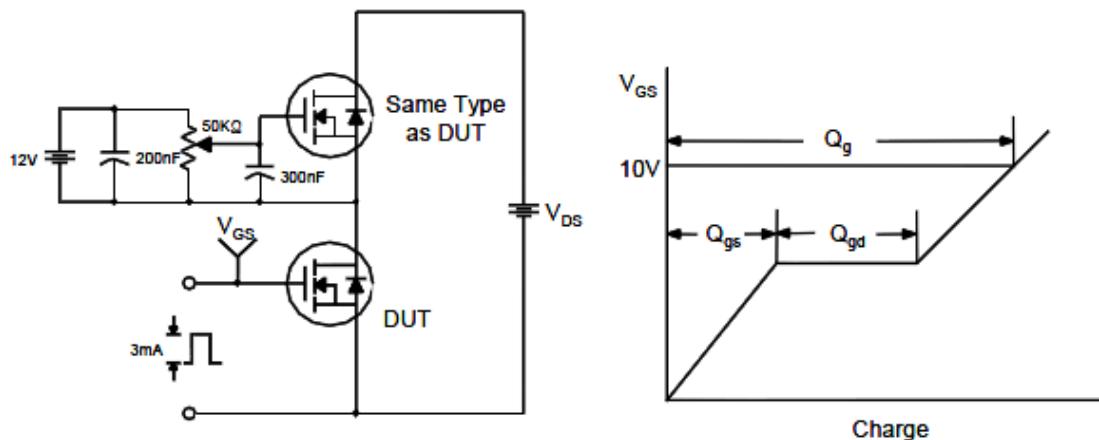


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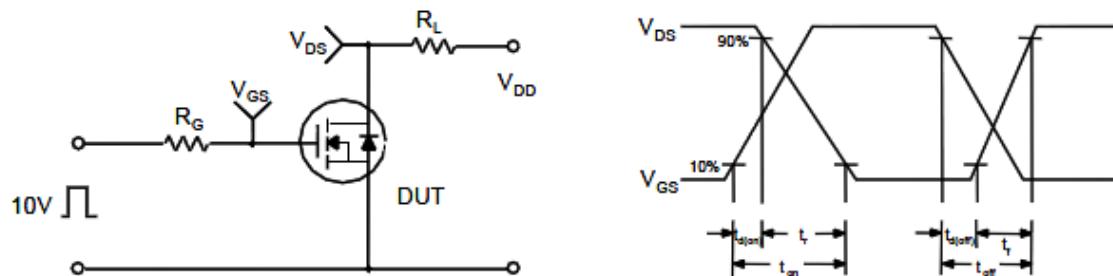
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Typical Characteristics

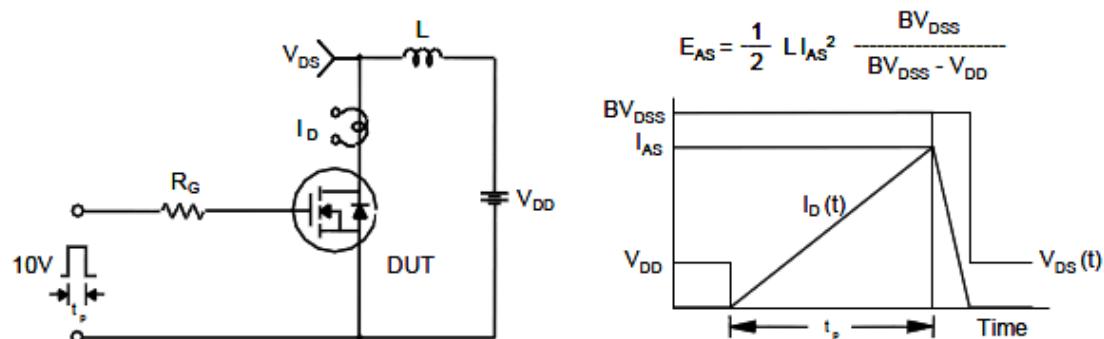
Gate Charge Test Circuit & Waveform



Resistive Switching Test Circuit & Waveforms



Unclamped Inductive Switching Test Circuit & Waveforms

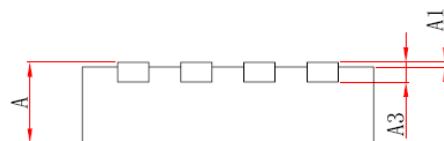
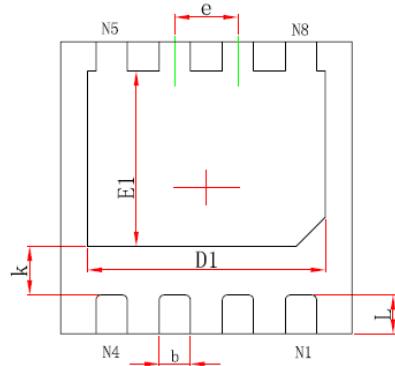
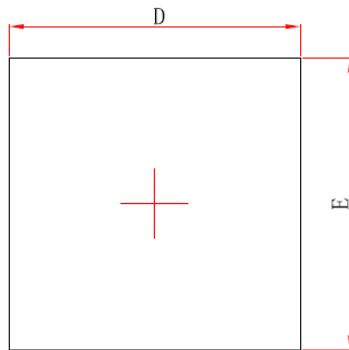




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Package Information (DFN3X3-8L)



Top View

Bottom View

Side View

Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.800	0.900	0.031	0.035
A1	0.000	0.050	0.000	0.002
A3	0.203REF.		0.008REF.	
D	2.924	3.076	0.115	0.121
E	2.924	3.076	0.115	0.121
D1	2.350	2.550	0.093	0.100
E1	1.700	1.900	0.067	0.075
k	0.450	0.550	0.018	0.022
b	0.270	0.370	0.011	0.015
e	0.650TYP.		0.026TYP.	
L	0.324	0.476	0.013	0.019

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